SiT3372

1 MHz to 220 MHz Ultra-low Jitter Differential VCXO

Features

- Any frequency between 1 MHz and 220 MHz accurate to 6 decimal places
- Widest pull range options: ±25, ±50, ±80, ±100, ±150, ±200, ±400, ±800, ±1600, ±3200 ppm
- 0.23 ps RMS phase jitter (typ) over 12 kHz to 20 MHz bandwidth
- Wide temperature range support from -40°C to 105°C
- Industry-standard packages: 7.0 x 5.0 mm, 5.0 x 3.2 mm, 3.2 x 2.5 mm packages
- For frequencies 220.000001 MHz to 720 MHz, refer to SiT3373

Applications

- Cable Modem Termination System (CMTS), Video, Broadcasting System, Audio, Industrial Sensors, Remote Radio Head (RRH)
- SATA, SAS, 10Gbps Ethernet, Fibre Channel, PCI-Express

Electrical Characteristics

Table 1. Electrical Characteristics – Common to LVPECL, LVDS and HCSL

All Min and Max limits in the Electrical Characteristics tables are specified over temperature and rated operating voltage with standard output termination show in the termination diagrams. Typical values are at 25°C and nominal supply voltage.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Frequency Range						
Output Frequency Range	f	1	–	220	MHz	Accurate to 6 decimal places
Frequency Stability						
Frequency Stability	F_stab	-15	–	+15	ppm	Inclusive of initial tolerance, operating temperature, rated power supply voltage, load variations, and first year aging at 25°C. Contact SiTime for ±15 ppm.
		-25	–	+25	ppm	
		-35	–	+35	ppm	
		-50	–	+50	ppm	
Temperature Range						
Operating Temperature Range	T_use	-20	–	+70	°C	Extended Commercial
		-40	–	+85	°C	Industrial.
		-40	–	+95	°C	
		-40	–	+105	°C	Extended Industrial
Supply Voltage						
Supply Voltage	Vdd	2.97	3.3	3.63	V	
		2.7	3.0	3.3	V	
		2.52	2.8	3.08	V	
		2.25	2.5	2.75	V	
Voltage Control Characteristics						
Pull Range	PR	±25, ±50, ±80, ±100, ±150, ±200, ±400, ±800, ±1600, ±3200			ppm	See the APR (Absolute Pull Range) Table 11. Contact SiTime for custom pull range options.
Upper Control Voltage	VC_U	90%	–	–	Vdd	Voltage at which maximum frequency deviation is guaranteed
Lower Control Voltage	VC_L	–	–	10%	Vdd	Voltage at which minimum frequency deviation is guaranteed
Control Voltage Input Impedance	VC_z	–	10	–	MΩ	
Control Voltage Input Bandwidth	V_c	–	10	–	kHz	Contact SiTime for other input bandwidth options
Pull Range Linearity	Lin	–	–	1.0	%	
Frequency Change Polarity	–	Positive Slope		–		
Input Characteristics						
Input Voltage High	VIH	70%	–	–	Vdd	Pin 2, OE
Input Voltage Low	VIL	–	–	30%	Vdd	Pin 2, OE
Input Pull-up Impedance	Z_in	–	100	-	kΩ	Pin 2, OE logic high or logic low
Output Characteristics						
Duty Cycle	DC	45	–	55	%	
Startup and OE Timing						
Startup Time	T_start	–	–	3.0	ms	Measured from the time Vdd reaches its rated minimum value.
OE Enable/Disable Time	T_oe	–	–	3.8	µs	f = 156.25 MHz. Measured from the time OE pin reaches rated VIH and VIL to the time clock pins reach 90% of swing and high-Z. See Figure 7 and Figure 8

Table 2. Electrical Characteristics – LVPECL Specific

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption	Idd	–	–	92	mA	Excluding Load Termination Current, Vdd = 3.3V or 2.5V
OE Disable Supply Current	I_OE	–	–	61	mA	OE = Low
Output Disable Leakage Current	I_leak	–	0.15	–	µA	OE = Low
Maximum Output Current	I_driver	–	–	33	mA	Maximum average current drawn from OUT+ or OUT-
Output Characteristics						
Output High Voltage	VOH	Vdd-1.15	–	Vdd-0.7	V	See Figure 3
Output Low Voltage	VOL	Vdd-2.0	–	Vdd-1.5	V	See Figure 3
Output Differential Voltage Swing	V_Swing	1.2	1.6	2.0	V	See Figure 4
Rise/Fall Time	Tr, Tf	–	225	290	ps	20% to 80%, see Figure 4
Jitter – 7.0 x 5.0 mm package						
RMS Period Jitter[1]	T_jitt	–	1.0	1.6	ps	f = 100, 156.25 or 212.5 MHz, Vdd = 3.3V or 2.5V
RMS Phase Jitter (random)	T_phj	–	0.225	0.270	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -20 to 70ºC and -40 to 85ºC.
		–	0.225	0.300	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -40 to 95 ºC and -40 to 105ºC
		–	0.1	–	ps	f = 156.25 or 322.265625 MHz, IEEE802.3-2005 10GbE jitter mask integration bandwidth = 1.875 MHz to 20 MHz, includes spurs, all Vdd levels.
Jitter – 5.0 x 3.2 mm and 3.2 x 2.5 mm package						
RMS Period Jitter[1]	T_jitt	–	1.0	1.6	ps	f = 100, 156.25 or 212.5 MHz, Vdd = 3.3V or 2.5V
RMS Phase Jitter (random)	T_phj	–	0.225	0.275	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -20 to 70ºC and -40 to 85ºC.
		–	0.225	0.340	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -40 to 95 ºC and -40 to 105ºC
		–	0.1	–	ps	f = 156.25 or 322.265625 MHz, IEEE802.3-2005 10GbE jitter mask integration bandwidth = 1.875 MHz to 20 MHz, includes spurs, all Vdd levels.

Notes:
1. Measured according to JESD65B

Table 3. Electrical Characteristics – LVDS

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption	Idd	–	–	84	mA	Excluding Load Termination Current, Vdd = 3.3V or 2.5V
OE Disable Supply Current	I_OE	–	–	62	mA	OE = Low
Output Disable Leakage Current	I_leak	–	0.15	–	µA	OE = Low
Output Characteristics						
Differential Output Voltage	VOD	250	–	450	mV	See Figure 5
VOD Magnitude Change	ΔVOD	–	–	50	mV	See Figure 5
Offset Voltage	VOS	1.125	–	1.375	V	See Figure 5
VOS Magnitude Change	ΔVOS	–	–	50	mV	See Figure 5
Rise/Fall Time	Tr, Tf	–	400	470	ps	Measured with 2 pF capacitive loading to GND, 20% to 80%, see Figure 6
Jitter – 7.0 x 5.0 mm package						
RMS Period Jitter[2]	T_jitt	–	1.0	1.6	ps	f = 100, 156.25 or 212.5 MHz, Vdd = 3.3V or 2.5V
RMS Phase Jitter (random)	T_phj	–	0.215	0.265	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -20 to 70ºC and -40 to 85ºC.
		–	0.215	0.300	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -40 to 95 ºC and -40 to 105ºC
		–	0.1	–	ps	f = 156.25 or 322.265625 MHz, IEEE802.3-2005 10GbE jitter mask integration bandwidth = 1.875 MHz to 20 MHz, includes spurs, all Vdd levels.
Jitter – 5.0 x 3.2 mm and 3.2 x 2.5 mm package						
RMS Period Jitter[2]	T_jitt	–	1.0	1.6	ps	f = 100, 156.25 or 212.5 MHz, Vdd = 3.3V or 2.5V
RMS Phase Jitter (random)	T_phj	–	0.235	0.275	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -20 to 70ºC and -40 to 85ºC.
		–	0.235	0.320	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -40 to 95 ºC and -40 to 105ºC
		–	0.1	–	ps	f = 156.25 or 322.265625 MHz, IEEE802.3-2005 10GbE jitter mask integration bandwidth = 1.875 MHz to 20 MHz, includes spurs, all Vdd levels.

Notes:
2. Measured according to JESD65B

Table 4. Electrical Characteristics – HCSL

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption	Idd	–	–	97	mA	Excluding Load Termination Current, Vdd = 3.3V or 2.5V
OE Disable Supply Current	I_OE	–	–	62	mA	OE = Low
Output Disable Leakage Current	I_leak	–	0.15	–	µA	OE = Low
Maximum Output Current	I_driver	–	–	35	mA	Maximum average current drawn from OUT+ or OUT-
Output Characteristics						
Output High Voltage	VOH	0.60	–	0.90	V	See Figure 3
Output Low Voltage	VOL	-0.05	–	0.08	V	See Figure 3
Output Differential Voltage Swing	V_Swing	1.2	1.4	1.80	V	See Figure 4
Rise/Fall Time	Tr, Tf	–	360	495	ps	Measured with 2 pF capacitive loading to GND, 20% to 80%, See Figure 4
Jitter – 7.0 x 5.0 mm package						
RMS Period Jitter[3]	T_jitt	–	1.0	1.6	ps	f = 100, 156.25 or 212.5 MHz, Vdd = 3.3V or 2.5V
RMS Phase Jitter (random)	T_phj	–	0.220	0.270	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -20 to 70ºC and -40 to 85ºC.
		–	0.220	0.300	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -40 to 95 ºC and -40 to 105ºC
		–	0.1	–	ps	f = 156.25 or 322.265625 MHz, IEEE802.3-2005 10GbE jitter mask integration bandwidth = 1.875 MHz to 20 MHz, includes spurs, all Vdd levels.
Jitter – 5.0 x 3.2 mm and 3.2 x 2.5 mm package						
RMS Period Jitter[3]	T_jitt	–	1.0	1.6	ps	f = 100, 156.25 or 212.5 MHz, Vdd = 3.3V or 2.5V
RMS Phase Jitter (random)	T_phj	–	0.230	0.275	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -20 to 70ºC and -40 to 85ºC.
		–	0.230	0.340	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all Vdd levels, includes spurs, pull range = 100 ppm. Temperature ranges -40 to 95 ºC and -40 to 105ºC
		–	0.1	–	ps	f = 156.25 or 322.265625 MHz, IEEE802.3-2005 10GbE jitter mask integration bandwidth = 1.875 MHz to 20 MHz, includes spurs, all Vdd levels.

Notes:
3. Measured according to JESD65B

Table 5. Pin Description

Pin	Symbol	Functionality	
1	VIN	Input	Control Voltage
2	NC/OE	No Connect (NC)	No Connect: Leave floating or connect to GND for better heat dissipation. NC for all 3.2 x 2.5 mm package options.
		Output Enable (OE)	H[4,5]: specified frequency output L: output is high impedance. Only output driver is disabled. OE function only available on 7050 package. Pin 2 on 3225 package is NC.
3	GND	Power	Vdd Power Supply Ground
4	OUT+	Output	Oscillator output
5	OUT-	Output	Complementary oscillator output
6	Vdd	Power	Power supply voltage[6]

Top View

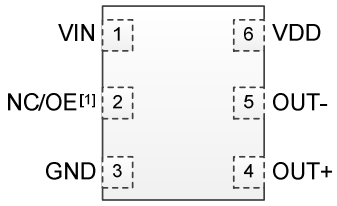


Figure 1. Pin Assignments (7.0 x 5.0 mm and 5.0 x 3.2 mm packages)

Top View

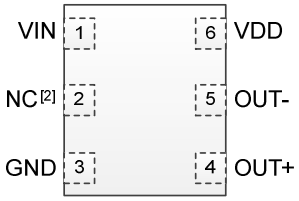


Figure 2. Pin Assignments (3.2 x 2.5 mm package)

Notes:

4. A pull-up resistor of 10 kΩ or less is recommended if pin 1 is not externally driven.
5. OE mode is only available in the 7050 and 5032 packages. 3225 package is NC.
6. A capacitor of value 0.1 µF or higher between Vdd and GND is required. An additional 10 µF capacitor between Vdd and GND is required for the best phase jitter performance.

Table 6. Absolute Maximum Ratings

Attempted operation outside the absolute maximum ratings may cause permanent damage to the part.
Actual performance of the IC is only guaranteed within the operational specifications, not at absolute maximum ratings.

Parameter	Min.	Max.	Unit
Vdd	-0.5	4.0	V
VIH		Vdd + 0.3V	V
VIL	-0.3		V
Storage Temperature	-65	150	ºC
Maximum Junction Temperature		130	ºC
Soldering Temperature (follow standard Pb-free soldering guidelines)		260	ºC

Table 7. Thermal Considerations[7]

Package	θ_{JA}, 4 Layer Board (°C/W)	θ_{JC}, Bottom (°C/W)
3225, 6-pin	80	30
5032, 6-pin	TBD	TBD
7050, 6-pin	52	19

Notes:
7. Refer to JESD51 for θ_{JA} and θ_{JC} definitions, and reference layout used to determine the θ_{JA} and θ_{JC} values in the above table.

Table 8. Maximum Operating Junction Temperature[8]

Max Operating Temperature (ambient)	Maximum Operating Junction Temperature
70°C	95°C
85°C	110°C
95°C	120°C
105°C	130°C

Notes:
8. Datasheet specifications are not guaranteed if junction temperature exceeds the maximum operating junction temperature.

Table 9. Environmental Compliance

Parameter	Test Conditions	Value	Unit
Mechanical Shock Resistance	**MIL-STD-883F, Method 2002**	10,000	*g*
Mechanical Vibration Resistance	**MIL-STD-883F, Method 2007**	70	*g*
Soldering Temperature (follow standard Pb free soldering guidelines)	**MIL-STD-883F, Method 2003**	260	°C
Moisture Sensitivity Level	**MSL1 @ 260°C**		
Electrostatic Discharge (HBM)	**HBM, JESD22-A114**	2,000	V
Charge-Device Model ESD Protection	**JESD220C101**	750	V
Latch-up Tolerance	**JESD78 Compliant**		

Waveform Diagrams

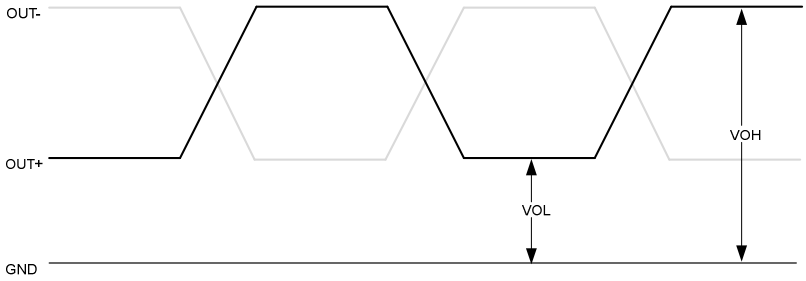


Figure 3. LVPECL/HCSL Voltage Levels per Differential Pin (OUT+/OUT-)

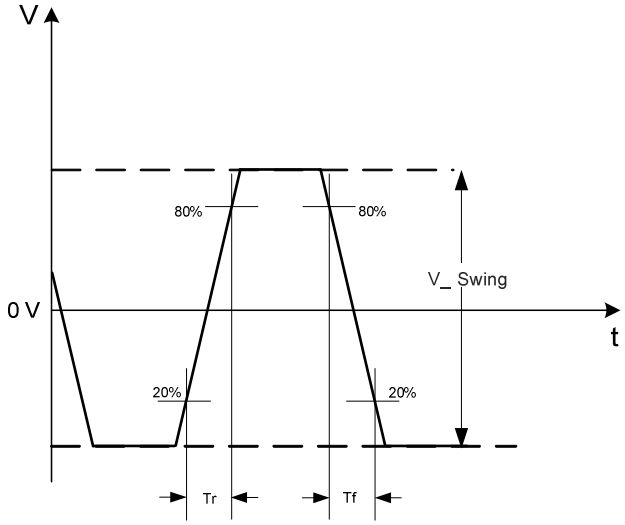


Figure 4. LVPECL/HCSL Voltage Levels across Differential Pair

Waveform Diagrams (continued)

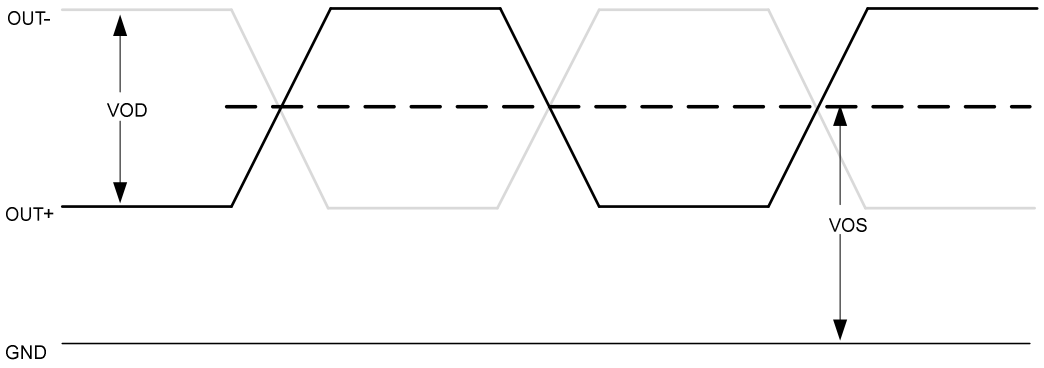


Figure 5. LVDS Voltage Levels per Differential Pin (OUT+/OUT-)

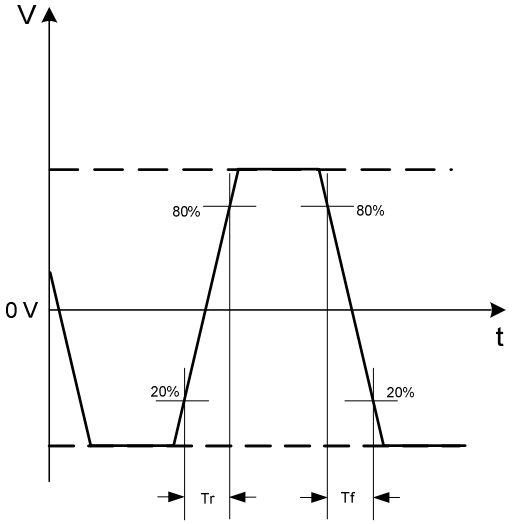


Figure 6. LVDS Differential Waveform

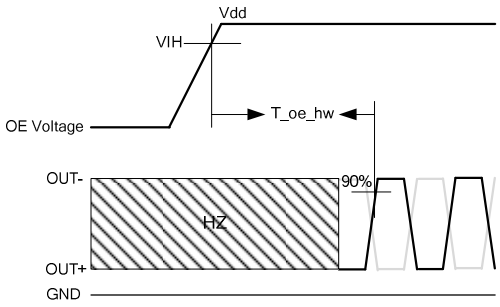


Figure 7. Hardware OE Enable Timing

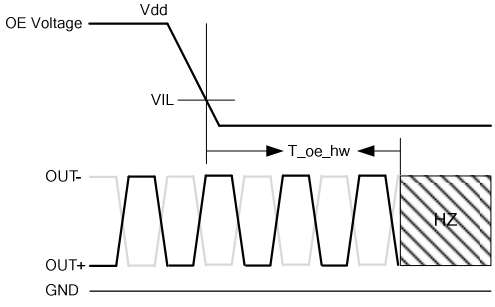


Figure 8. Hardware OE Disable Timing

Termination Diagrams

LVPECL:

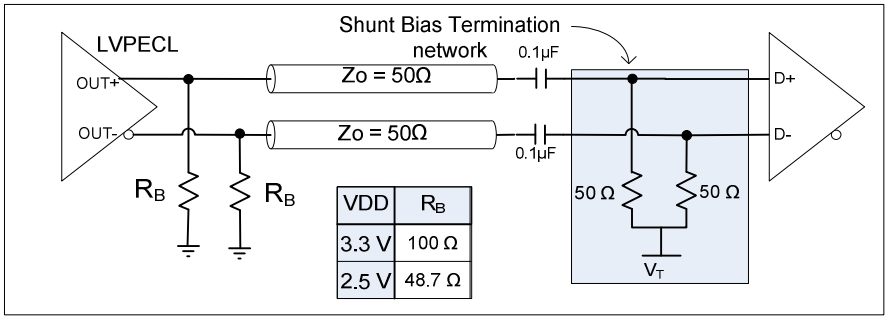


Figure 9. LVPECL with AC-coupled termination

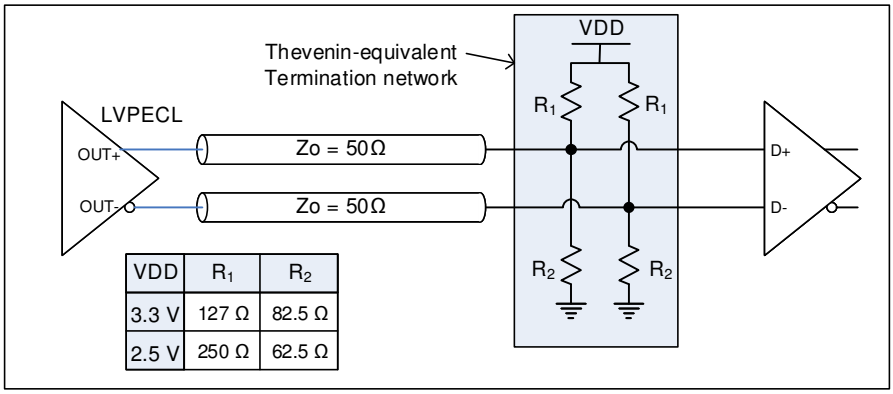


Figure 10. LVPECL DC-coupled load termination with Thevenin equivalent network

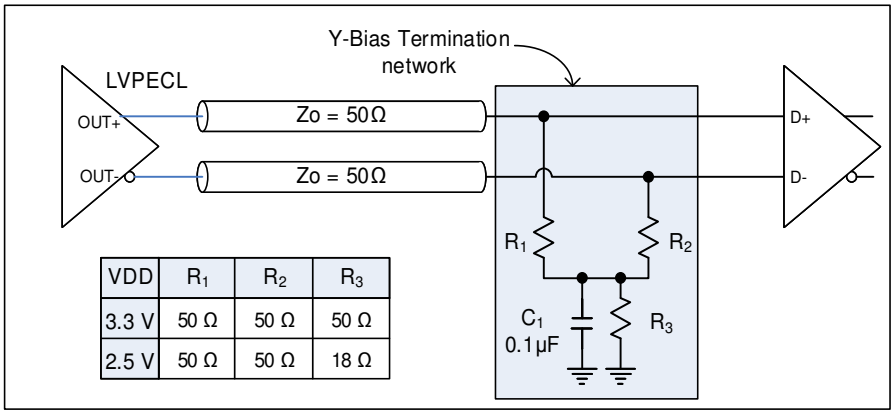


Figure 11. LVPECL with Y-Bias termination

Termination Diagrams (continued)

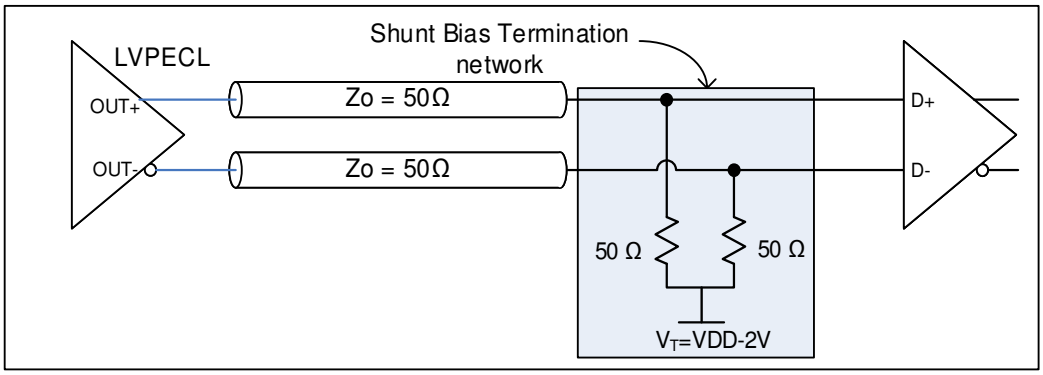


Figure 12. LVPECL with DC-coupled parallel shunt load termination

Termination Diagrams (continued)

LVDS:

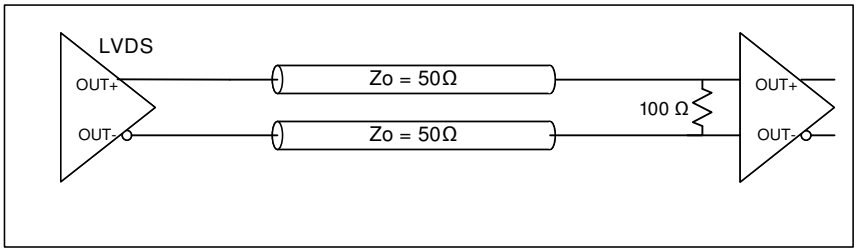


Figure 13. LVDS single DC termination at the load

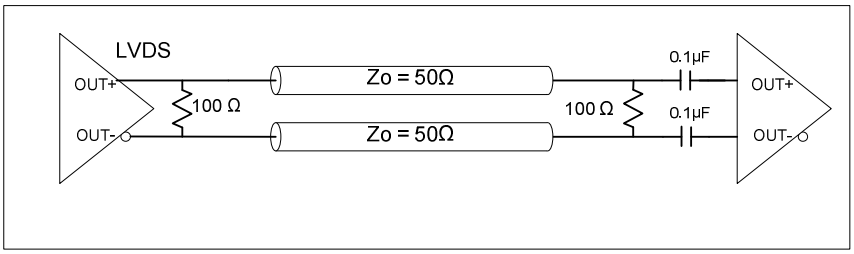


Figure 14. LVDS double AC termination with capacitor close to the load

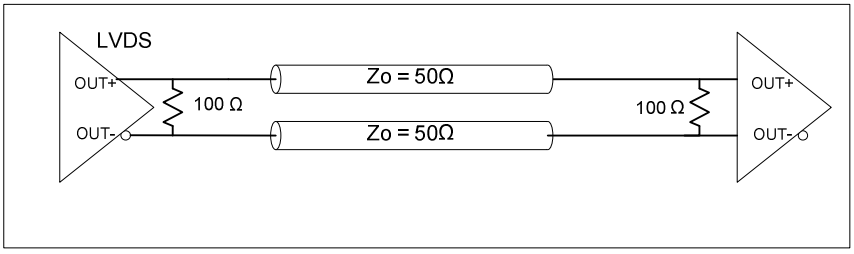


Figure 15. LVDS double DC termination

Termination Diagrams (continued)

HCSL:

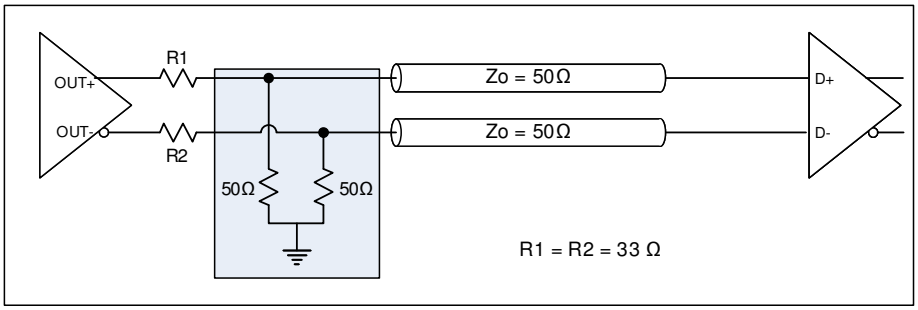
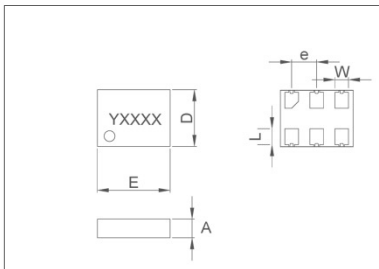


Figure 16. HCSL interface termination

Dimensions and Patterns

Package Size – Dimensions (Unit: mm)[9]	Recommended Land Pattern (Unit: mm)[10]

3.2 x 2.5 x 0.85 mm



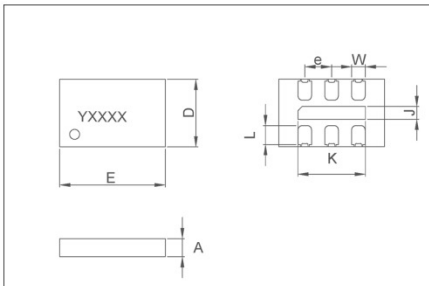
Dimension Table

		Symbol	Min	Nom	Max
TOTAL THICKNESS		A	0.800	0.850	0.900
BODY SIZE	X	D	2.400	2.500	2.600
	Y	E	3.200	3.200	3.300
LEAD PITCH		e	1.100 BSC		
LEAD LENGTH		L	0.650	0.700	0.750
LEAD WIDTH		W	0.550	0.600	0.650

6L QFN	Package Outline
3.2 x 2.5 x 0.75 mm	
POD-38 Rev A	

3.2 x 2.5 x 0.85 mm

5.0 x 3.2 x 0.85 mm[11]

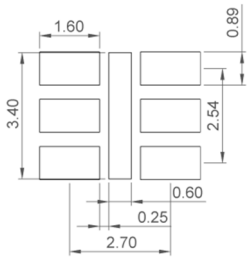


Dimension Table

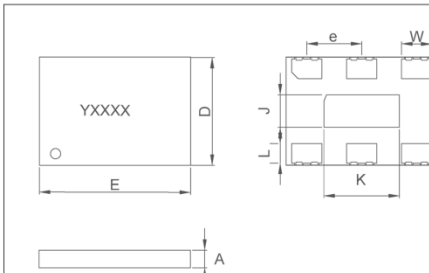
		Symbol	Min	Nom	Max
TOTAL THICKNESS		A	0.800	0.850	0.900
BODY SIZE	X	D	3.100	3.200	3.300
	Y	E	4.900	5.000	5.100
EP SIZE	X	J	0.500	0.600	0.700
	Y	K	3.100	3.200	3.300
LEAD PITCH		e	1.270 BSC		
LEAD LENGTH		L	0.850	0.900	0.950
LEAD WIDTH		W	0.590	0.640	0.690

6L QFN	Package Outline
5.0 x 3.2 x 0.85 mm	
POD-39 Rev A	

5.0 x 3.2 x 0.85 mm[11]



7.0 x 5.0 x 0.85 mm[11]

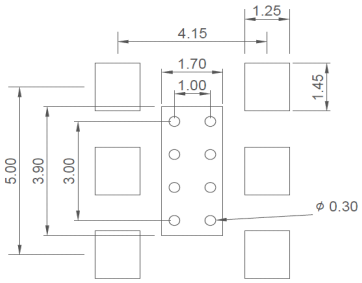


Dimension Table

		Symbol	Min	Nom	Max
TOTAL THICKNESS		A	0.800	0.850	0.900
BODY SIZE	X	D	4.900	5.000	5.100
	Y	E	6.900	7.000	7.100
EP SIZE	X	J	1.400	1.500	1.600
	Y	K	3.400	3.500	3.600
LEAD PITCH		e	2.540 BSC		
LEAD LENGTH		L	0.850	0.900	0.950
LEAD WIDTH		W	1.350	1.400	1.450

6L QFN	Package Outline
7.0 x 5.0 x 0.90 mm	
POD-37 Rev A	

7.0 x 5.0 x 0.85 mm[11]

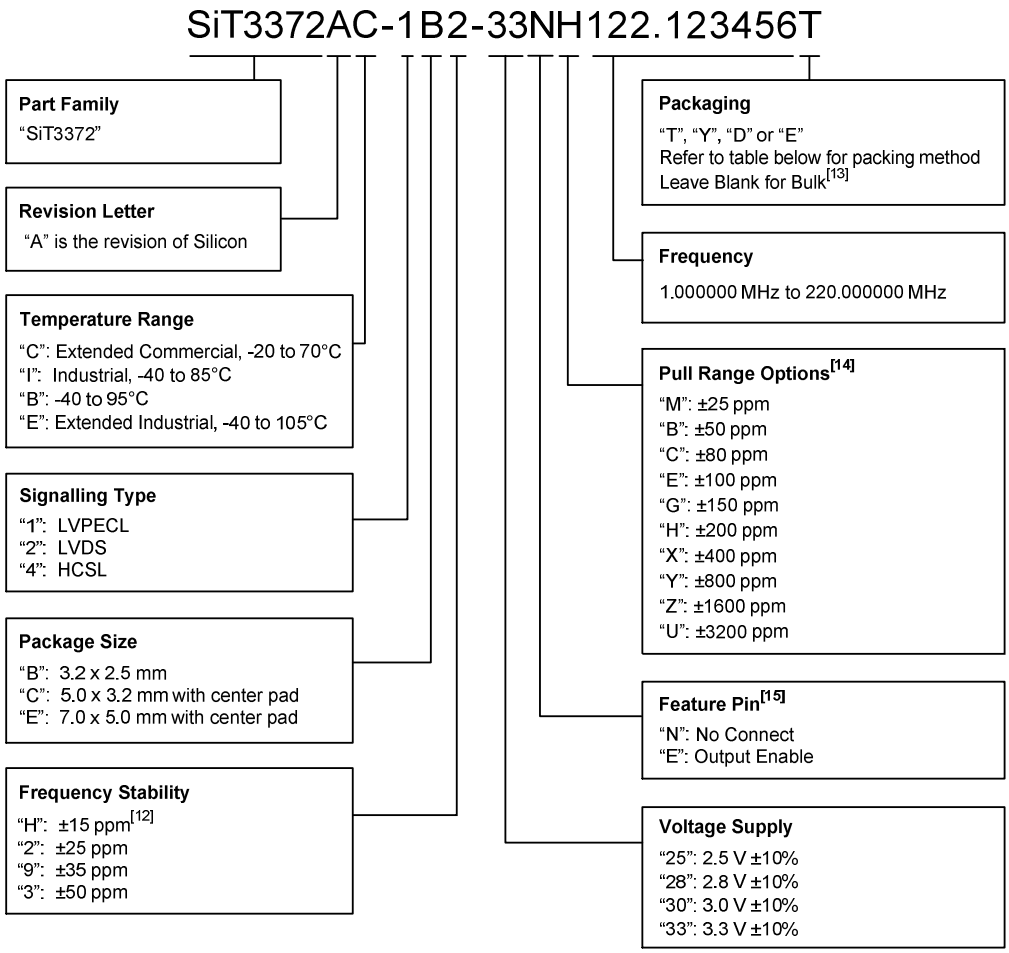


Note:
Circles in center pad are thermal vias, recommended to improve thermal performance

Notes:

9. Top Marking: Y denotes manufacturing origin and XXXX denotes manufacturing lot number. The value of "Y" will depend on the assembly location of the device.
10. A capacitor of value 0.1 µF or higher between Vdd and GND is required. An additional 10 µF capacitor between Vdd and GND is required for the best phase jitter performance
11. The center pad has no electrical function. Soldering down the center pad to the GND is recommended for best thermal dissipation, but is optional.

Ordering Information



Notes:

12. Contact SiTime for ±15 ppm
13. Bulk is available for sampling only
14. Contact SiTime for custom pull range options
15. "E": Output Enable function is only available in 7.0 x 5.0 mm and 5.0 x 3.2 mm packages

Table 10. Ordering Codes for Supported Tape & Reel Packing Method

Device Size (mm x mm)	8 mm T&R (3ku)	8 mm T&R (1ku)	12 mm T&R (3ku)	12 mm T&R (1ku)	16 mm T&R (3ku)	16 mm T&R (1ku)
7.0 x 5.0	—	—	—	—	T	Y
5.0 x 3.2	—	—	T	Y	—	—
3.2 x 2.5	D	E	T	Y	—	—

Table 11. APR Table

Absolute pull range (APR) = Nominal pull range (PR) - frequency stability (F_stab)-aging

Nominal Pull Range	Frequency Stability			
	± 15	± 25	± 35	±50
	APR (ppm)			
± 25	± 5	—	—	—
± 50	± 30	± 20	± 10	—
± 80	± 60	± 50	± 40	± 25
± 100	± 80	± 70	± 60	± 45
± 150	± 130	± 120	± 110	± 95
± 200	± 180	± 170	± 160	± 145
± 400	± 380	± 370	± 360	± 345
± 800	± 780	± 770	± 760	± 745
± 1600	± 1580	± 1570	± 1560	± 1545
± 3200	± 3180	± 3170	± 3160	± 3145

Table 12. Additional Information

Document	Description	Download Link
ECCN #: EAR99	Five character designation used on the commerce Control List (CCL) to identify dual use items for export control purposes.	—
Part number Generator	Tool used to create the part number based on desired features.	—
Manufacturing Notes	Tape & Reel dimension, reflow profile and other manufacturing related info	http://www.sitime.com/manufacturing-notes
Product Qualification report	Device reliability report	https://www.sitime.com/sites/default/files/gated/RR45_Third%20Generation%20DEXO%2C%20VCXO%20Product%20Qualification%20Report_A01.pdf
Environmental Reports	RoHS report	https://www.sitime.com/sites/default/files/gated/QI-86 RoHSCert_Third Generation DEXO, VCXO Package_Homogeneous_Materials_A00.pdf
Composition report	Get from Robin	https://www.sitime.com/sites/default/files/gated/QI-87%20Third%20Generation%20DEXO%2C%20VCXO%20Composition%20Report_A01_0.pdf
Performance Reports	Additional performance data such as phase noise, current consumption and jitter for selected frequencies	http://www.sitime.com/support/performance-measurement-report
Termination Techniques	Termination design recommendations	http://www.sitime.com/support/application-notes
Layout Techniques	Layout recommendations	http://www.sitime.com/support/application-notes

Table 13. Revision History

Revision	Release Date	Change Summary
1.0	10/13/2017	Initial release
1.03	05/10/2018	Updated the Part Ordering info with added 5.0 x 3.2 mm package

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